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Vishay Siliconix

P-Channel 30 V (D-S) MOSFET

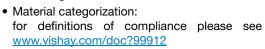


Marking code: BT

PRODUCT SUMMARY						
V _{DS} (V)	-30					
$R_{DS(on)}$ max. (Ω) at $V_{GS} = -10 \text{ V}$	0.0312					
$R_{DS(on)}$ max. (Ω) at $V_{GS} = -4.5 \text{ V}$	0.0513					
Q _g typ. (nC)	4.5					
I _D (A) a, d	-8					
Configuration	Single					

FEATURES

- TrenchFET® Gen IV p-channel power MOSFET
- \bullet 100 % R_g and UIS tested

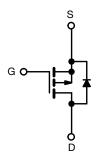




ROHS COMPLIANT HALOGEN FREE

APPLICATIONS

Load switch



P-Channel MOSFET

ORDERING INFORMATION	
Package	TSOP-6
Lead (Pb)-free and halogen-free	Si3483DDV-T1-GE3

ABSOLUTE MAXIMUM RATINGS (T _A = 25 °C, unparameter Drain-source voltage Gate-source voltage		SYMBOL	LIMIT	UNIT	
		V _{DS}	-30	V	
		V _{GS}	-20 / +16		
<u> </u>	T _C = 25 °C		-8 ^a		
Outline and the count (T 450.00)	T _C = 70 °C		-6.4		
Continuous drain current (T _J = 150 °C)	T _A = 25 °C	I _D	-6.4 ^{b, c}		
	T _A = 70 °C		-5.2 ^{b, c}	А	
Pulsed drain current (t = 100 µs)		I _{DM}	-30		
Octobra de la desta de la constitución de la consti	T _C = 25 °C		-2.5		
Continuous source-drain diode current	T _A = 25 °C	I _S	-1.67 ^{b, c}		
	T _C = 25 °C		3		
Maximum power dissipation	T _C = 70 °C	_	2	147	
	T _A = 25 °C	P _D	2 b, c	W	
	T _A = 70 °C		1.3 ^{b, c}		
Operating junction and storage temperature range		T _J , T _{sta}	-55 to +150	°C	

THERMAL RESISTANCE RATINGS						
PARAMETER		SYMBOL	TYPICAL	MAXIMUM	UNIT	
Maximum junction-to-ambient ^b	t ≤ 5 s	R_{thJA}	52	62.5	°C/W	
Maximum junction-to-case (drain)	Steady state	R_{thJC}	34	41		

Notes

- a. Package limited
- b. Surface mounted on 1" x 1" FR4 board
- c. t = 5 s
- d. Maximum under steady state conditions is 110 °C/W

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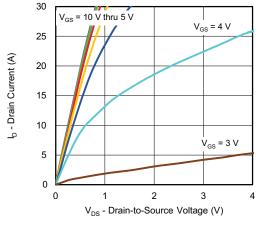
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
Static					l	1
Drain-source breakdown voltage	V_{DS}	$V_{GS} = 0 \text{ V}, I_D = -250 \mu\text{A}$	-30	-	-	V
V _{DS} temperature coefficient	$\Delta V_{DS}/T_{J}$		-	-17.6	-	m\//°C
V _{GS(th)} temperature coefficient	$\Delta V_{GS(th)}/T_J$	I _D = -250 μA	-	5	-	mV/°C
Gate-source threshold voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$	-1	-	-2.2	V
Gate-source leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = -20 \text{ V} / +16 \text{ V}$	-	-	± 100	nA
Zana and a self-an adaptive and a		$V_{DS} = -30 \text{ V}, V_{GS} = 0 \text{ V}$	-	-	-1	μА
Zero gate voltage drain current	I _{DSS}	V _{DS} = -30 V, V _{GS} = 0 V, T _J = 70 °C	-	-	-10	
On-state drain current ^a	I _{D(on)}	$V_{DS} \ge -10 \text{ V}, V_{GS} = -10 \text{ V}$	-5	-	-	Α
Daile and a second seco	5	$V_{GS} = -10 \text{ V}, I_D = -5 \text{ A}$	-	0.0260	0.0312	
Drain-source on-state resistance ^a	R _{DS(on)}	$V_{GS} = -4.5 \text{ V}, I_D = -3 \text{ A}$	-	0.0410	0.0513	Ω
Forward transconductance a	9 _{fs}	V _{DS} = -10 V, I _D = -5 A	-	30	-	S
Dynamic ^b			l	•		•
Input capacitance	C _{iss}		-	580	-	
Output capacitance	C _{oss}	$V_{DS} = -15 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$	-	245	-	pF
Reverse transfer capacitance	C _{rss}		-	35	-	1
Total gate charge	Qg	$V_{DS} = -15 \text{ V}, V_{GS} = -10 \text{ V}, I_D = -6.4 \text{ A}$	-	9.5	14.5	nC
			-	4.5	9	
Gate-source charge	Q _{gs}	$V_{DS} = -15 \text{ V}, V_{GS} = -4.5 \text{ V}, I_{D} = -6.4 \text{ A}$	-	2.6	-	
Gate-drain charge	Q_{gd}		-	1.3	-	
Gate resistance	R_g	f = 1 MHz	3.4	20	34	Ω
Turn-on delay time	t _{d(on)}		-	15	30	
Rise time	t _r	$V_{DD} = -15 \text{ V}, R_L = 2.9 \Omega, I_D \cong -5.2 \text{ A},$	-	33	66	
Turn-off delay time	t _{d(off)}	$V_{GEN} = -10 \text{ V}, R_g = 1 \Omega$	-	30	60	1
Fall time	t _f		-	40	60	
Turn-on delay time	t _{d(on)}		-	26	52	ns
Rise time	t _r	V_{DD} = -15 V, R_L = 2.9 Ω , $I_D \cong$ -5.2 A,	-	140	280	1
Turn-off delay time	t _{d(off)}	$V_{GEN} = -4.5 \text{ V}, R_g = 1 \Omega$	-	26	52	1
Fall time	t _f		-	42	84	1
Drain-Source Body Diode Characteristi	cs		I.	•	! 	
Continuous source-drain diode current	Is	T _C = 25 °C	-	-	-2.5	_
Pulse diode forward current	I _{SM}		-	-	-30	A
Body diode voltage	V_{SD}	$I_{S} = -5.2 \text{ A}, V_{GS} = 0 \text{ V}$	-	-0.8	-1.2	V
Body diode reverse recovery time	t _{rr}		-	21	32	ns
Body diode reverse recovery charge	Q _{rr}	$I_F = -5.2 \text{ A}, \text{ di/dt} = 100 \text{ A/}\mu\text{s},$	-	9	18	nC
Reverse recovery fall time	ta	$T_J = 25 ^{\circ}\text{C}$	-	9	-	
Reverse recovery rise time	t _b		-	12	-	ns

Notes

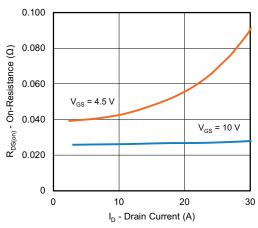
- a. Pulse test; pulse width \leq 300 µs, duty cycle \leq 2 %
- b. Guaranteed by design, not subject to production testing

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

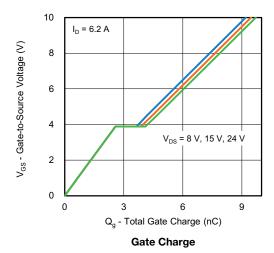


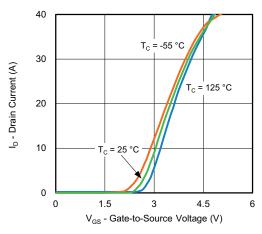


Output Characteristics

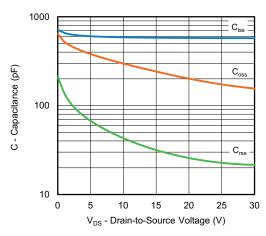


On-Resistance vs. Drain Current and Gate Voltage

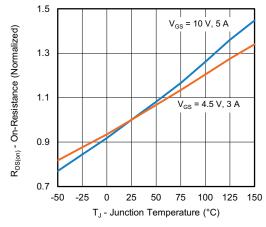




Transfer Characteristics

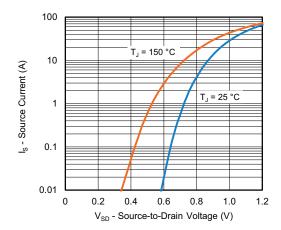


Capacitance

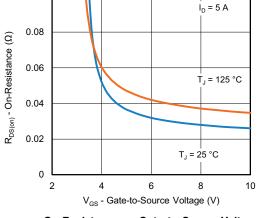


On-Resistance vs. Junction Temperature



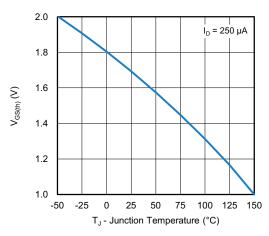


Source-Drain Diode Forward Voltage

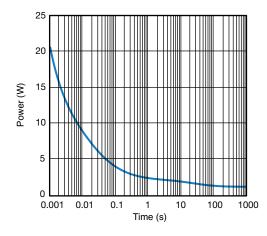


0.10

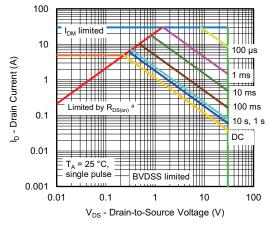
On-Resistance vs. Gate-to-Source Voltage



Threshold Voltage



Single Pulse Power, Junction-to-Ambient

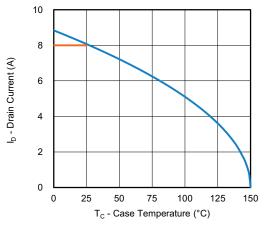


Safe Operating Area, Junction-to-Ambient

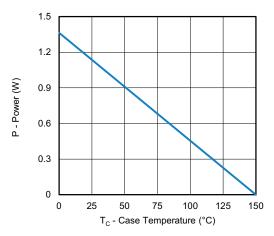
Note

a. V_{GS} > minimum V_{GS} at which $R_{DS(on)}$ is specified

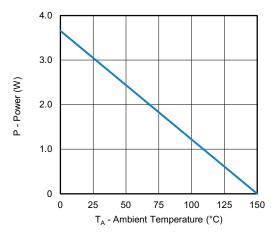




Current Derating a





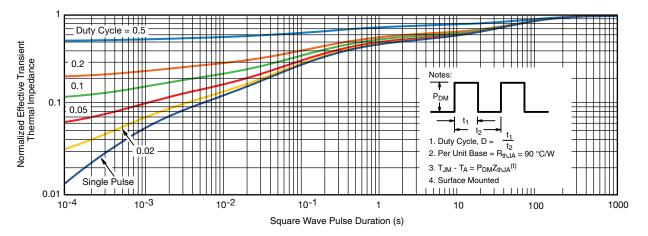


Power, Junction-to-Ambient

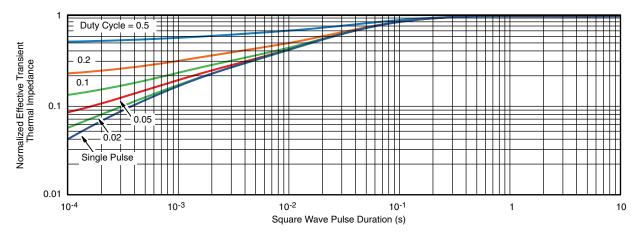
Note

a. The power dissipation P_D is based on T_J max. = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit





Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Case

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package / tape drawings, part marking, and reliability data, see www.vishay.com/ppg?76252.





TSOP: 5/6-LEAD

JEDEC Part Number: MO-193C





5-LEAD TSOP







	MIL	LIMETER	RS	INCHES			
Dim	Min	Nom	Max	Min	Nom	Max	
Α	0.91	-	1.10	0.036	-	0.043	
A ₁	0.01	-	0.10	0.0004	-	0.004	
A ₂	0.90	-	1.00	0.035	0.038	0.039	
b	0.30	0.32	0.45	0.012	0.013	0.018	
С	0.10	0.15	0.20	0.004	0.006	0.008	
D	2.95	3.05	3.10	0.116	0.120	0.122	
Е	2.70	2.85	2.98	0.106	0.112	0.117	
E ₁	1.55	1.65	1.70	0.061	0.065	0.067	
е		0.95 BSC		0.0374 BSC			
e ₁	1.80	1.90	2.00	0.071	0.075	0.079	
L	0.32	-	0.50	0.012	-	0.020	
L ₁		0.60 Ref		0.024 Ref			
L ₂	0.25 BSC			0.010 BSC			
R	0.10	-	-	0.004	-	-	
θ	0°	4°	8°	0°	4°	8°	
θ1	7° Nom				7° Nom		
ECN: C-06593-Rev. I, 18-Dec-06 DWG: 5540							

Document Number: 71200 18-Dec-06



Recommended Land Pattern For TSOP-5L / TSOP-6L



Note

• All dimensions are in inches (millimeter)

ECN: C22-0860-Rev. B, 24-Oct-2022 DWG: 3010



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